

DISPLAY Elektronik GmbH

DATA SHEET

TFT MODULE

DEM 240320M1 VMH-PW-N
3,2" TFT

Product Specification

Ver.: 8

11.12.2023

Revision History

Revision	Date	Originator	Detail	Remarks
0	30.06.2022	J	Initial Release	
1	01.07.2022	J	Modify the Module Parameter Modify the Optical Characteristics Modify the Interface Pins Definition Modify the Outline Drawing	P4 P6 P10 P23
2	31.08.2022	J	Modify the Weight and the Backlight Characteristics	P4
3	01.09.2022	J	Modify the Backlight Characteristics	P6
4	12.07.2023	L	Change Driver IC and backlight thickness	P4, P23
5	30.08.2023	L	Modify the Backlight Unit	P5, P6, P23
6	05.09.2023	L	Modify the drawing	P23
7	07.12.2023	ZWC	Modify Packing	.
8	08.12.2023	ZWC	Modify the Power Dissipation	P5

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1. General Description

The specification is a transmissive type color active matrix liquid crystal display (LCD) which uses amorphous thin film transistor (TFT) as switching devices. This product is composed of a TFT-LCD panel, driver ICs and a backlight unit.

2. Module Parameter

Features	Details	Unit
Display Size(Diagonal)	3.2"	-
LCD Type	IPS TFT	-
Display Mode	Transmissive / Normally black	-
Resolution	240 RGB x 320	Pixels
View Direction	Full view	Best Image
Gray Scale Inversion Direction	-	-
Module Outline	55.04 x 77.70 x 2.45 (Note1)	mm
Active Area	48.60 x 64.80	mm
Pixel Size	0.2025 x 0.2025	mm
Pixel Arrangement	R.G.B. Vertical Stripe	-
Display Colors	262K	-
Interface	16-BIT-MCU, 8-BIT-MCU, SPI Interface	-
With or without Touch Panel	Without	-
Driver IC	ST7789T3 (Sitronix)	-
Operating Temperature	-20 to +70	°C
Storage Temperature	-30 to +80	°C
Weight	~ 19	g

Note 1: Exclusive hooks, posts, FFC/FPC tail etc.

3. Absolute Maximum Ratings

$V_{SS}=0V$, $T_a=25^{\circ}C$

Item	Symbol	Min.	Max.	Unit
Supply Voltage	VCI	-0.3	4.6	V
	IOVCC	-0.3	4.6	-
Storage Temperature	T _{stg}	-30	+80	°C
Operating Temperature	T _{op}	-20	+70	°C

Note 1: If T_a below $50^{\circ}C$, the maximal humidity is 90%RH, if T_a over $50^{\circ}C$, absolute humidity should be less than 60%RH.

Note 2: The response time will be extremely slow when the operating temperature is around $-10^{\circ}C$, and the back ground will become darker at high temperature operating.

4. DC Characteristics

Item	Symbol	Min.	Typ.	Max.	Unit	
Supply Voltage	V _{CI}	2.5	2.8	3.3	V	
	IOVCC	1.65	2.8	3.3	V	
Logic Low input voltage	V _{IL}	GND	-	0.3*V _{CI}	V	
Logic High input voltage	V _{IH}	0.7*V _{CI}	-	V _{CI}	V	
Logic Low output voltage	V _{OL}	GND	-	0.2*V _{CI}	V	
Logic High output voltage	V _{OH}	0.8*V _{CI}	-	V _{CI}	V	
Current Consumption All Black	Logic	I _{CC+ I_{IN}}	-	9	-	mA
	Analog					

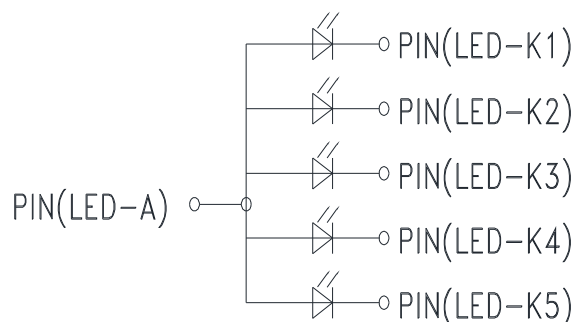
5. Backlight Characteristic

5.1. Backlight Characteristics

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V _F	T _a =25 °C, I _F =20mA/LED	2.8	3.2	3.4	V
Forward Current	I _F	T _a =25 °C, V _F =3.2V/LED	-	100	-	mA
Power Dissipation	P _D		-	320	-	mW
Uniformity	Avg		80	-	-	%
LED Lifetime (25°C)	-		20000	30,000	-	Hrs
Drive Method	Constant Current					
LED Configuration	6 White LEDs in parallel					

Note1: LED life time defined as follows: The final brightness is at 50% of original brightness.
 The environmental conducted under ambient air flow, at T_a=25°C±2°C, 60%RH±5%, I_F=20mA/LED.

5.2. Backlighting Circuit



6. Optical Characteristics

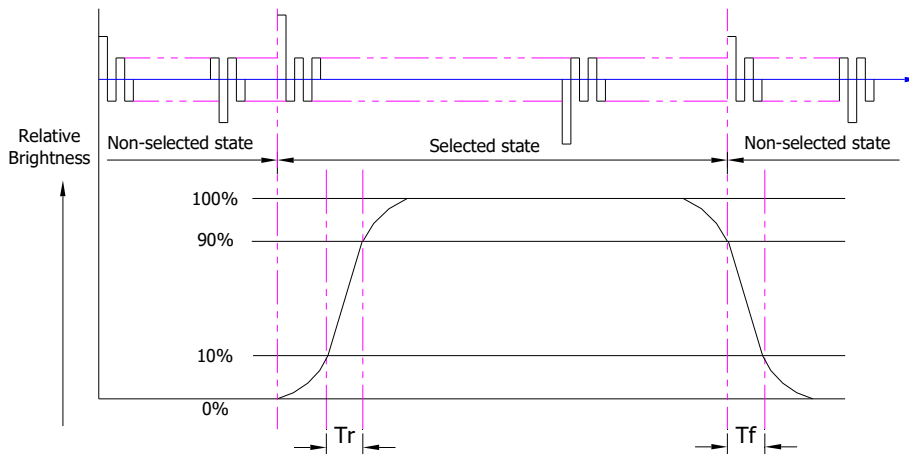
6.1. Optical Characteristics

Ta=25°C, VCI=2.8V

Backlight On (Transmissive Mode)	Item	Symbol	Condition	Specification			Unit	
				Min.	Typ.	Max.		
	Luminance on TFT($I_f=20\text{mA/LED}$)	Lv	Normally viewing angle $\theta_x = \phi_y = 0^\circ$	-	380	-	cd/m ²	
	Contrast ratio(See 6.3)	CR		800	1000	-	-	
	Response time (See 6.2)	T _{R+T_F}		-	25	35	ms	
	Chromaticity Transmissive (See 6.5)	White		X _w	0.300	0.315	0.330	-
			Y _w	0.334	0.349	0.364		
	Viewing Angle (See 6.4)	Horizontal	θ_{x+}	Center CR≥10	80	89	-	Deg.
			θ_{x-}		80	89	-	
		Vertical	ϕ_{y+}		80	89	-	
ϕ_{y-}			80		89	-		
NTSC Ratio(Gamut)				55	60	-	%	

6.2. Definition of Response Time

6.2.1. Normally Black Type (Negative)

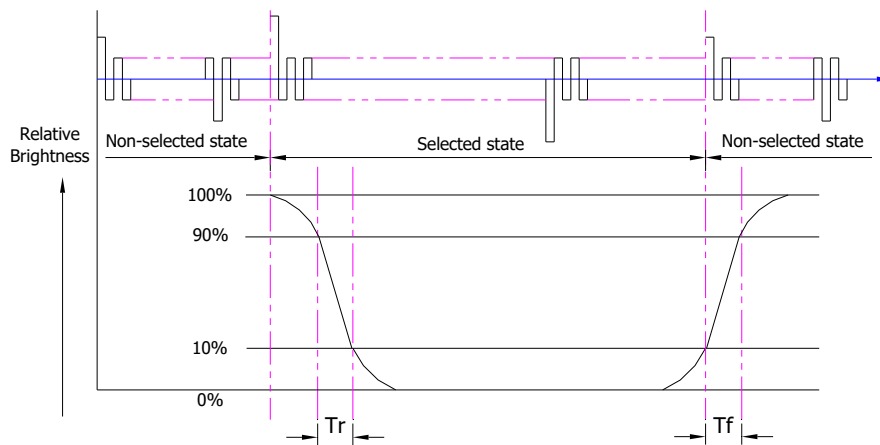


Tr is the time it takes to change from non-selected stage with relative luminance 10% to selected state with relative luminance 90%;

Tf is the time it takes to change from selected state with relative luminance 90% to non-selected state with relative luminance 10%.

Note : Measuring machine: LCD-5100

6.2.2. Normally White Type (Positive)



Tr is the time it takes to change from non-selected stage with relative luminance 90% to selected state with relative luminance 10%;

Tf is the time it takes to change from selected state with relative luminance 10% to non-selected state with relative luminance 90%;

Note: Measuring machine: LCD-5100 or EQUI

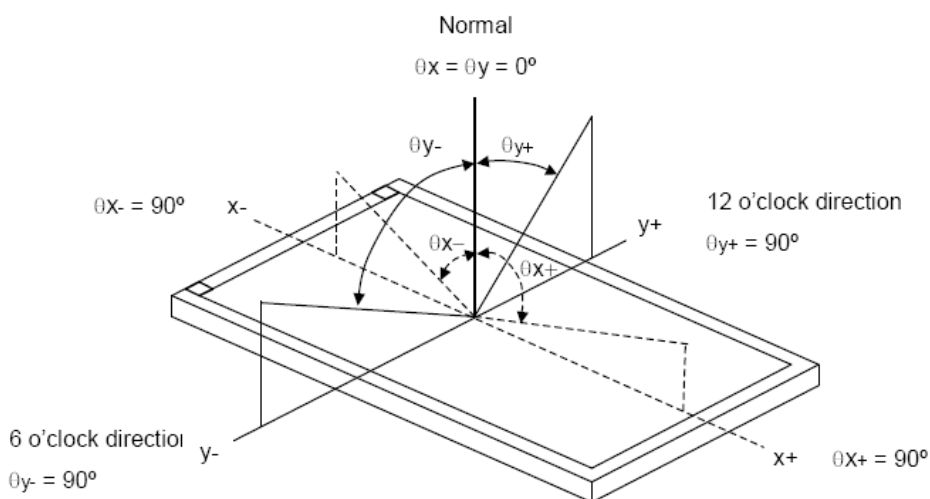
6.3. Definition of Contrast Ratio

Contrast is measured perpendicular to display surface in reflective and transmissive mode. The measurement condition is:

Measuring Equipment	Eldim or Equivalent
Measuring Point Diameter	3mm//1mm
Measuring Point Location	Active Area centre point
Test Pattern	A: All Pixels white B: All Pixel black
Contrast Setting	Maximum

Definitions: CR (Contrast) = Luminance of White Pixel / Luminance of Black Pixel

6.4. Definition of Viewing Angles



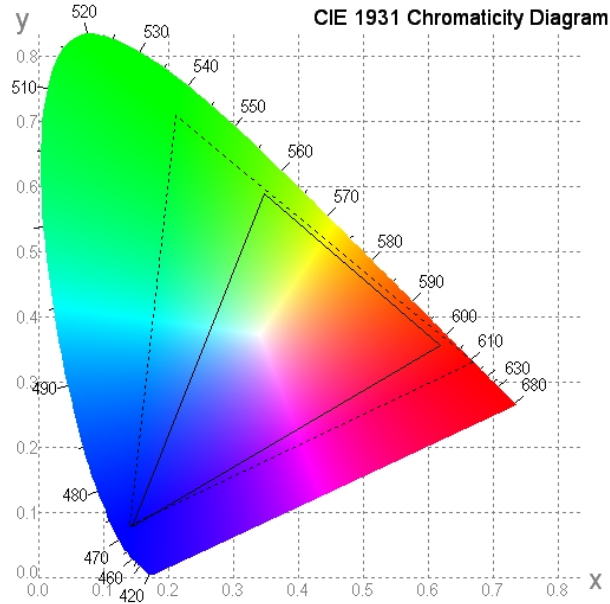
Measuring machine: LCD-5100 or EQUI

6.5. Definition of Color Appearance

R,G,B and W are defined by (x, y) on the IE chromaticity diagram

NTSC=area of RGB triangle/area of NTSC triangleX100%

Measuring picture: Red, Green, Blue and White (Measuring machine: BM-7)



6.6. Definition of Surface Luminance, Uniformity and Transmittance

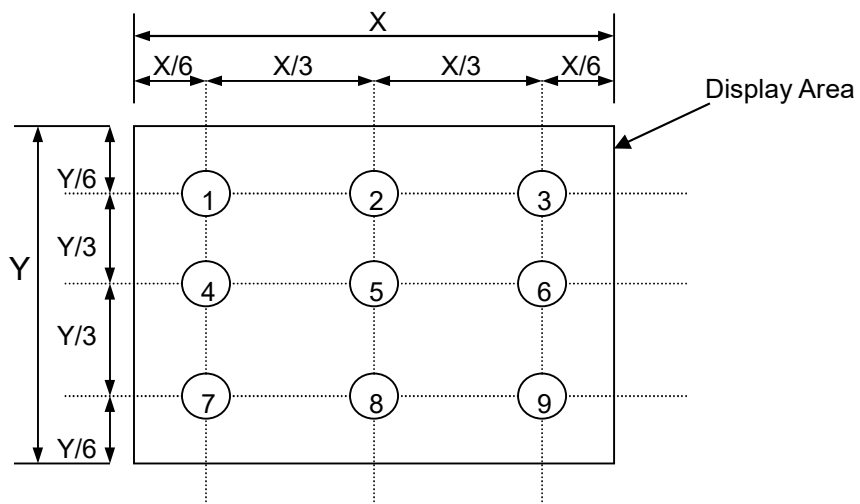
Using the transmissive mode measurement approach, measure the white screen luminance of the display panel and backlight.

6.6.1. Surface Luminance: $L_v = \text{average} (L_{P1}:L_{P9})$

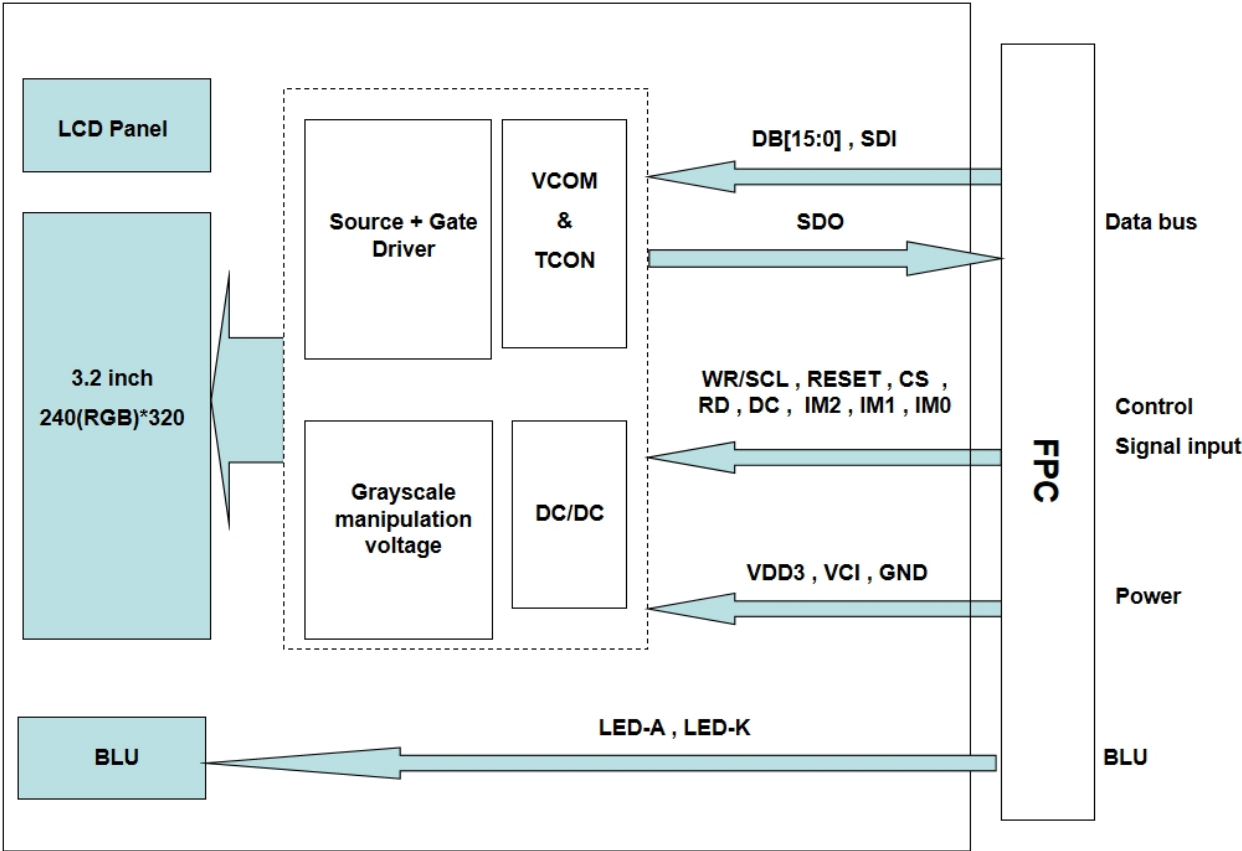
6.6.2. Uniformity = $\text{Minimal} (L_{P1}:L_{P9}) / \text{Maximal} (L_{P1}:L_{P9}) * 100\%$

6.6.3. Transmittance = $L_v \text{ on LCD} / L_v \text{ on Backlight} * 100\%$

Note: Measuring machine: BM-7



7. Block Diagram and Power Supply

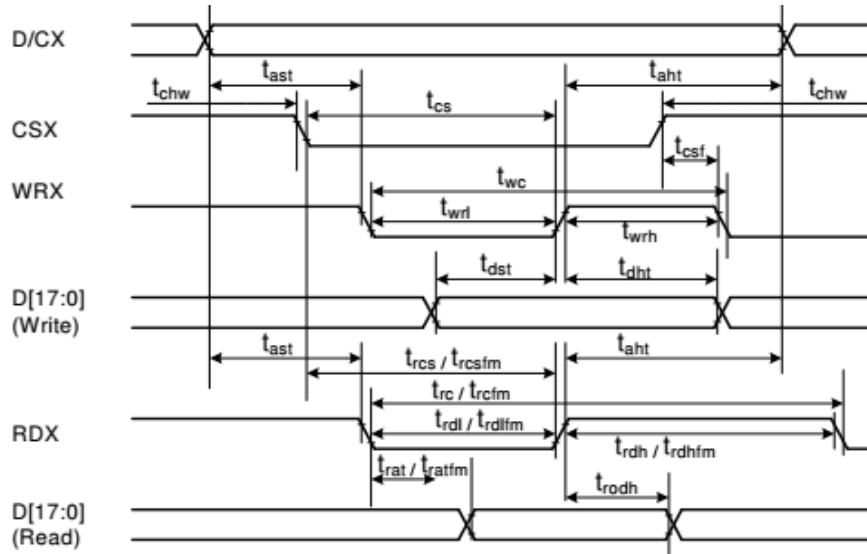


8. Interface Pins Definition

No.	Symbol	Function	Remark																									
1	NC(XL)	NC /Touch panel control pin																										
2	NC(YU)	NC /Touch panel control pin																										
3	NC(XR)	NC /Touch panel control pin																										
4	NC(YD)	NC /Touch panel control pin																										
5	GND	Ground																										
6	IOVCC	Power supply for LCM (1.8V-3.3V)																										
7	VCI	Power supply for LCM (2.8V-3.3V)																										
8	FMARK	Tearing effect output pin																										
9	CS	Chip select pin ("Low" enable)																										
10	RS	This pin is used to select "Data or Command"																										
11	WR	Serves as a write signal and writes data at the rising edge																										
12	RD	Serves as a read signal and MCU read data at the rising edge																										
13	SDA	Serial input signal																										
14	SDO	Serial output signal																										
15	RESET	LCM Reset pin Signal is active low																										
16	GND	Ground																										
17	DB0	Data bus																										
18	DB1	Data bus																										
19	DB2	Data bus																										
20	DB3	Data bus																										
21	DB4	Data bus																										
22	DB5	Data bus																										
23	DB6	Data bus																										
24	DB7	Data bus																										
25	DB8	Data bus																										
26	DB9	Data bus																										
27	DB10	Data bus																										
28	DB11	Data bus																										
29	DB12	Data bus																										
30	DB13	Data bus																										
31	DB14	Data bus																										
32	DB15	Data bus																										
33	LEDA	Anode of Backlight																										
34	LEDK	Cathode of Backlight																										
35	LEDK	Cathode of Backlight																										
36	LEDK	Cathode of Backlight																										
37	GND	Ground																										
38	IM0	<table border="1"> <thead> <tr> <th>IM0</th> <th>IM1</th> <th>IM2</th> <th>Data pin</th> <th>MPU Interface Mode</th> </tr> </thead> <tbody> <tr> <td>0</td> <td>0</td> <td>0</td> <td>DB[0:15]</td> <td>80-16bit parallel</td> </tr> <tr> <td>1</td> <td>0</td> <td>0</td> <td>DB[8:15]</td> <td>80-8bit parallel</td> </tr> <tr> <td>1</td> <td>0</td> <td>1</td> <td>SDA:IN SDO:OUT</td> <td>3-line 9bit serial</td> </tr> <tr> <td>0</td> <td>1</td> <td>1</td> <td>SDA:IN SDO:OUT</td> <td>4-line 8bit serial</td> </tr> </tbody> </table>	IM0	IM1	IM2	Data pin	MPU Interface Mode	0	0	0	DB[0:15]	80-16bit parallel	1	0	0	DB[8:15]	80-8bit parallel	1	0	1	SDA:IN SDO:OUT	3-line 9bit serial	0	1	1	SDA:IN SDO:OUT	4-line 8bit serial	Select the MCU interface mode
IM0	IM1		IM2	Data pin	MPU Interface Mode																							
0	0		0	DB[0:15]	80-16bit parallel																							
1	0		0	DB[8:15]	80-8bit parallel																							
1	0	1	SDA:IN SDO:OUT	3-line 9bit serial																								
0	1	1	SDA:IN SDO:OUT	4-line 8bit serial																								
39	IM1																											
40	IM2																											

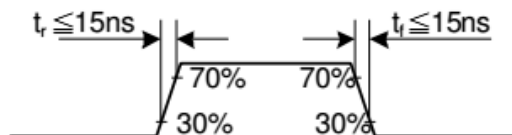
9. AC Characteristics

Display Parallel 16-bit Interface Timing Characteristics

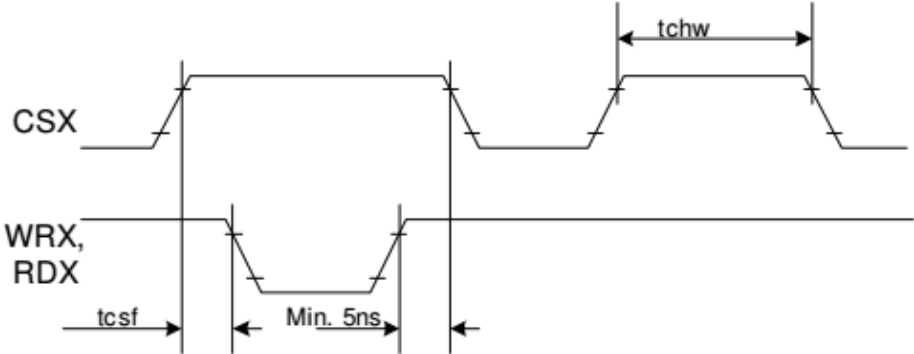


Signal	Symbol	Parameter	min	max	Unit	Description
DCX	t _{ast}	Address setup time	0	-	ns	
	t _{ah}	Address hold time (Write/Read)	0	-	ns	
CSX	t _{chw}	CSX "H" pulse width	0	-	ns	
	t _{cs}	Chip Select setup time (Write)	15	-	ns	
	t _{r_{cs}}	Chip Select setup time (Read ID)	45	-	ns	
	t _{r_{csfm}}	Chip Select setup time (Read FM)	355	-	ns	
WRX	t _{csf}	Chip Select Wait time (Write/Read)	10	-	ns	
	t _{wc}	Write cycle	66	-	ns	
	t _{wrl}	Write Control pulse L duration	15	-	ns	
RDX (FM)	t _{wrh}	Write Control pulse H duration	15	-	ns	
	t _{rdl}	Read Control pulse L duration	15	-	ns	
	t _{rdh}	Read Control pulse H duration	15	-	ns	
RDX (FM)	t _{rcfm}	Read Cycle (FM)	450	-	ns	
	t _{rdhfm}	Read Control H duration (FM)	90	-	ns	
	t _{rdlfm}	Read Control L duration (FM)	355	-	ns	
RDX (ID)	t _{rc}	Read cycle (ID)	160	-	ns	
	t _{rdh}	Read Control pulse H duration	90	-	ns	
	t _{rdl}	Read Control pulse L duration	45	-	ns	
D[17:0], D[15:0], D[8:0], D[7:0]	t _{dst}	Write data setup time	10	-	ns	For maximum CL=30pF For minimum CL=8pF
	t _{dht}	Write data hold time	10	-	ns	
	t _{rat}	Read access time	-	40	ns	
	t _{ratfm}	Read access time	-	340	ns	
	t _{rodh}	Read output disable time	20	80	ns	

Note: T_a = -30 to 70 °C, VDDI=1.65V to 3.3V, VCI=2.5V to 3.3V, VSS=0V

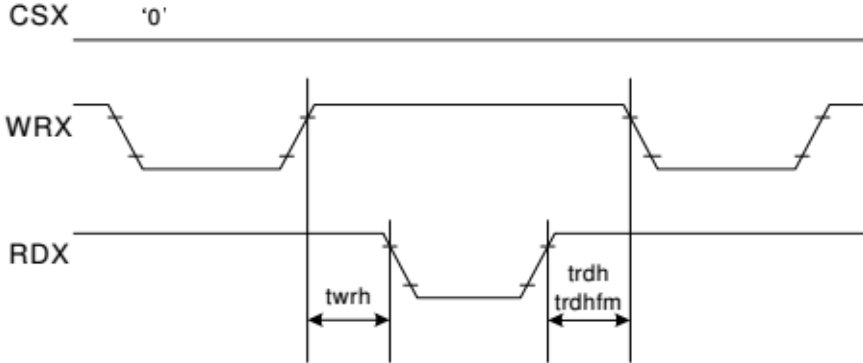


CSX timings :



Note: Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.

Write to read or read to write timings:



Note: Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.

10. Quality Assurance

10.1.Purpose

This standard for Quality Assurance assures the quality of LCD module products supplied to customer.

10.2.Standard for Quality Test

10.2.1. Sampling Plan:

GB2828.1-2012

Single sampling, general inspection level II

10.2.2. Sampling Criteria:

Visual inspection: AQL 1.5%

Electrical functional: AQL 0.65%.

10.2.3. Reliability Test:

Detailed requirement refer to Reliability Test Specification.

10.3.Nonconforming Analysis & Disposition

10.3.1. Nonconforming analysis:

10.3.1.1. Customer should provide overall information of non-conforming sample for their complaints.

10.3.1.2. After receipt of detailed information from customer, the analysis of nonconforming parts usually should be finished in one week.

10.3.1.3. If cannot finish the analysis on time, customer will be notified with the progress status.

10.3.2. Disposition of nonconforming:

10.3.2.1. Non-conforming product over PPM level will be replaced.

10.3.2.2. The cause of non-conformance will be analyzed. Corrective action will be discussed and implemented.

10.4.Agreement Items

Shall negotiate with customer if the following situation occurs:

10.4.1. There is any discrepancy in standard of quality assurance.

10.4.2. Additional requirement to be added in product specification.

10.4.3. Any other special problem.

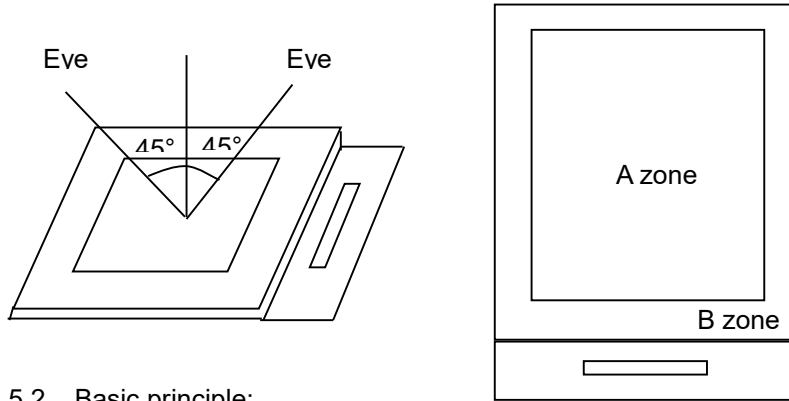
10.5.Standard of the Product Visual Inspection

10.5.1. Appearance inspection:

10.5.1.1. The inspection must be under illumination about 1000 – 1500 lx, and the distance of view must be at 30cm ± 2cm.

10.5.1.2. The viewing angle should be 45° from the vertical line without reflection light or follows customer's viewing angle specifications.

10.5.1.3. Definition of area: A Zone: Active Area, B Zone: Viewing Area,

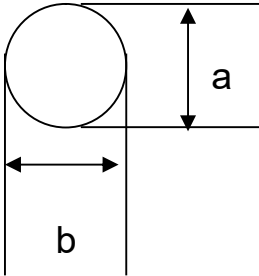


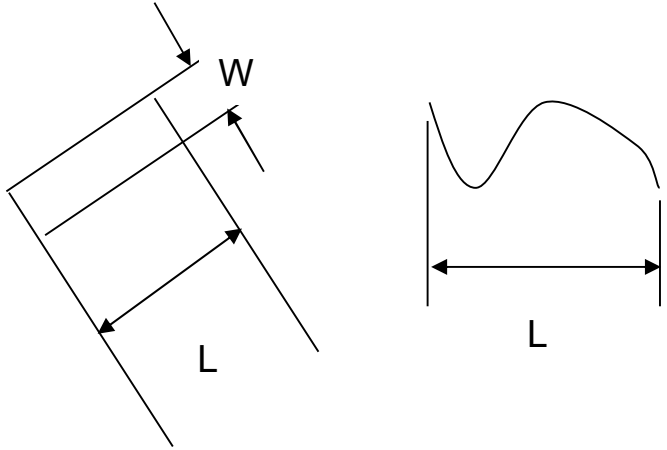
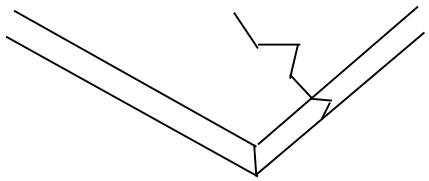
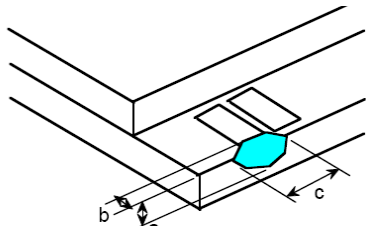
10.5.2. Basic principle:

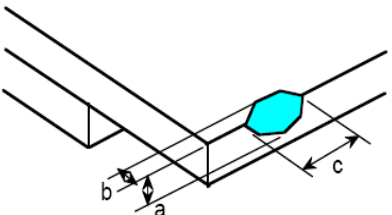
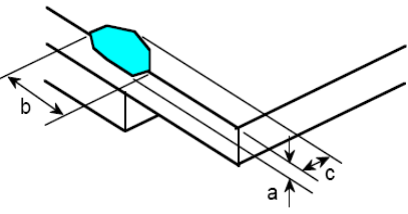
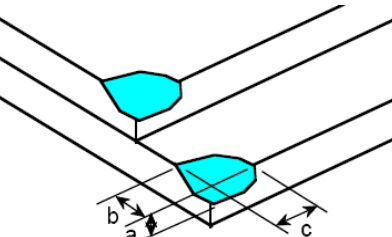
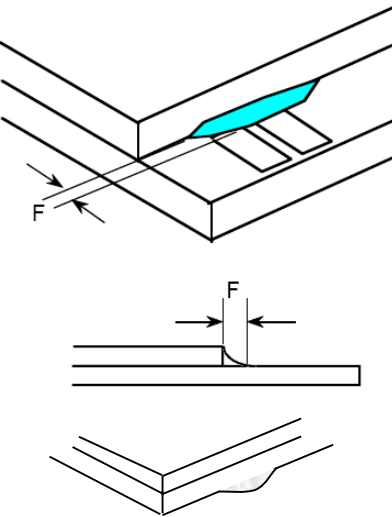
10.5.2.1. A set of sample to indicate the limit of acceptable quality level must be discussed by both us and customer when there is any dispute happened.

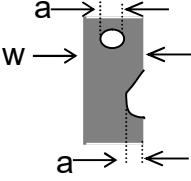
10.5.2.2. New item must be added on time when it is necessary.

10.6. Inspection Specification

No.	Item	Criteria (Unit: mm)																		
01	Black / White spot Foreign material (Round type) Pinholes Stain Particles inside cell. (Minor defect)	 <table border="1" data-bbox="938 931 1441 1272"> <thead> <tr> <th>Size \ Area</th> <th>Acc. Qty</th> </tr> </thead> <tbody> <tr> <td>$\phi \leq 0.10$</td> <td>Ignore</td> </tr> <tr> <td>$0.10 < \phi \leq 0.15$</td> <td>2</td> </tr> <tr> <td>$0.15 < \phi \leq 0.25$</td> <td>1</td> </tr> <tr> <td>$0.25 < \phi$</td> <td>0</td> </tr> <tr> <td>Total</td> <td>2 no include $\phi \leq 0.10$</td> </tr> </tbody> </table> <p>$\phi = (a + b) / 2$ Distance between 2 defects should more than 3mm apart.</p>	Size \ Area	Acc. Qty	$\phi \leq 0.10$	Ignore	$0.10 < \phi \leq 0.15$	2	$0.15 < \phi \leq 0.25$	1	$0.25 < \phi$	0	Total	2 no include $\phi \leq 0.10$						
Size \ Area	Acc. Qty																			
$\phi \leq 0.10$	Ignore																			
$0.10 < \phi \leq 0.15$	2																			
$0.15 < \phi \leq 0.25$	1																			
$0.25 < \phi$	0																			
Total	2 no include $\phi \leq 0.10$																			
02	Electrical Defect (Minor defect)	<table border="1" data-bbox="557 1373 1378 1590"> <thead> <tr> <th></th> <th>Display Area</th> <th>Total</th> <th></th> </tr> </thead> <tbody> <tr> <td>Bright dot</td> <td>0</td> <td>0</td> <td rowspan="3">Note1</td> </tr> <tr> <td>Dark dot</td> <td>$N \leq 2$</td> <td>$N \leq 2$</td> </tr> <tr> <td>Total dot</td> <td>$N \leq 2$</td> <td>$N \leq 2$</td> </tr> <tr> <td>Mura</td> <td colspan="2">Not visible through 5% ND filters.</td> <td>Note2</td> </tr> </tbody> </table> <p>Remark: 1. Bright dot caused by scratch and foreign object accords to item 1.</p>		Display Area	Total		Bright dot	0	0	Note1	Dark dot	$N \leq 2$	$N \leq 2$	Total dot	$N \leq 2$	$N \leq 2$	Mura	Not visible through 5% ND filters.		Note2
	Display Area	Total																		
Bright dot	0	0	Note1																	
Dark dot	$N \leq 2$	$N \leq 2$																		
Total dot	$N \leq 2$	$N \leq 2$																		
Mura	Not visible through 5% ND filters.		Note2																	

<p>03</p>	<p>Black and White line Scratch Foreign material (Line type) (Minor defect)</p>	 <table border="1" data-bbox="614 801 1241 1111"> <thead> <tr> <th>Length</th> <th>Width</th> <th>Acc. Qty</th> </tr> </thead> <tbody> <tr> <td>/</td> <td>$W \leq 0.03$</td> <td>Ignore</td> </tr> <tr> <td>$L \leq 2.5$</td> <td>$0.03 < W \leq 0.05$</td> <td>3</td> </tr> <tr> <td>$L \leq 2.5$</td> <td>$0.05 < W \leq 0.10$</td> <td>2</td> </tr> <tr> <td>/</td> <td>$0.1 < W$</td> <td></td> </tr> <tr> <td colspan="2">Total</td> <td>3</td> </tr> </tbody> </table> <p>Distance between 2 defects should more than 3mm apart. Scratches not viewable through the back of the display are acceptable.</p>	Length	Width	Acc. Qty	/	$W \leq 0.03$	Ignore	$L \leq 2.5$	$0.03 < W \leq 0.05$	3	$L \leq 2.5$	$0.05 < W \leq 0.10$	2	/	$0.1 < W$		Total		3
Length	Width	Acc. Qty																		
/	$W \leq 0.03$	Ignore																		
$L \leq 2.5$	$0.03 < W \leq 0.05$	3																		
$L \leq 2.5$	$0.05 < W \leq 0.10$	2																		
/	$0.1 < W$																			
Total		3																		
<p>04</p>	<p>Glass Crack (Minor defect)</p>	 <p>Crack is potential to enlarge, any type is not allowed.</p>																		
<p>05</p>	<p>Glass Chipping Pad Area: (Minor defect)</p> 	<table border="1" data-bbox="877 1653 1353 1825"> <thead> <tr> <th>Length and Width</th> <th>Acc. Qty</th> </tr> </thead> <tbody> <tr> <td>$c > 3.0, b < 1.0$</td> <td>1</td> </tr> <tr> <td>$c < 3.0, b < 1.0$</td> <td>3</td> </tr> <tr> <td colspan="2">$a < \text{Glass Thickness}$</td> </tr> </tbody> </table>	Length and Width	Acc. Qty	$c > 3.0, b < 1.0$	1	$c < 3.0, b < 1.0$	3	$a < \text{Glass Thickness}$											
Length and Width	Acc. Qty																			
$c > 3.0, b < 1.0$	1																			
$c < 3.0, b < 1.0$	3																			
$a < \text{Glass Thickness}$																				

<p>06</p>	<p>Glass Chipping Rear of Pad Area: (Minor defect)</p> 	<table border="1"> <thead> <tr> <th>Length and Width</th> <th>Acc. Qty</th> </tr> </thead> <tbody> <tr> <td>$c > 3.0, b < 1.0$</td> <td>1</td> </tr> <tr> <td>$c < 3.0, b < 1.0$</td> <td>2</td> </tr> <tr> <td>$c < 3.0, b < 0.5$</td> <td>4</td> </tr> <tr> <td colspan="2" style="text-align: center;">$a < \text{Glass Thickness}$</td> </tr> </tbody> </table>	Length and Width	Acc. Qty	$c > 3.0, b < 1.0$	1	$c < 3.0, b < 1.0$	2	$c < 3.0, b < 0.5$	4	$a < \text{Glass Thickness}$	
Length and Width	Acc. Qty											
$c > 3.0, b < 1.0$	1											
$c < 3.0, b < 1.0$	2											
$c < 3.0, b < 0.5$	4											
$a < \text{Glass Thickness}$												
<p>07</p>	<p>Glass Chipping Except Pad Area: (Minor defect)</p> 	<table border="1"> <thead> <tr> <th>Length and Width</th> <th>Acc. Qty</th> </tr> </thead> <tbody> <tr> <td>$c > 3.0, b < 1.0$</td> <td>1</td> </tr> <tr> <td>$c < 3.0, b < 1.0$</td> <td>2</td> </tr> <tr> <td>$c < 3.0, b < 0.5$</td> <td>4</td> </tr> <tr> <td colspan="2" style="text-align: center;">$a < \text{Glass Thickness}$</td> </tr> </tbody> </table>	Length and Width	Acc. Qty	$c > 3.0, b < 1.0$	1	$c < 3.0, b < 1.0$	2	$c < 3.0, b < 0.5$	4	$a < \text{Glass Thickness}$	
Length and Width	Acc. Qty											
$c > 3.0, b < 1.0$	1											
$c < 3.0, b < 1.0$	2											
$c < 3.0, b < 0.5$	4											
$a < \text{Glass Thickness}$												
<p>08</p>	<p>Glass Corner Chipping: (Minor defect)</p> 	<table border="1"> <thead> <tr> <th>Length and Width</th> <th>Acc. Qty</th> </tr> </thead> <tbody> <tr> <td>$c < 3.0, b < 3.0$</td> <td>Ignore</td> </tr> <tr> <td colspan="2" style="text-align: center;">$a < \text{Glass Thickness}$</td> </tr> </tbody> </table>	Length and Width	Acc. Qty	$c < 3.0, b < 3.0$	Ignore	$a < \text{Glass Thickness}$					
Length and Width	Acc. Qty											
$c < 3.0, b < 3.0$	Ignore											
$a < \text{Glass Thickness}$												
<p>09</p>	<p>Glass Burr: (Minor defect)</p> 	<table border="1"> <thead> <tr> <th>Length</th> <th>Acc. Qty</th> </tr> </thead> <tbody> <tr> <td>$F < 1.0$</td> <td>Ignore</td> </tr> </tbody> </table> <p>Glass burr don't affect assemble and module dimension.</p>	Length	Acc. Qty	$F < 1.0$	Ignore						
Length	Acc. Qty											
$F < 1.0$	Ignore											

10	<p>FPC Defect: (Minor defect)</p> 	<p>10.1 Dent, pinhole width $a < w/3$. (w: circuitry width.) 10.2 Open circuit is unacceptable. 10.3 No oxidation, contamination and distortion.</p>										
11	Bubble on Polarizer (Minor defect)	<table border="1" data-bbox="758 548 1225 761"> <thead> <tr> <th>Diameter</th> <th>Acc. Qty</th> </tr> </thead> <tbody> <tr> <td>$\varphi \leq 0.20$</td> <td>Ignore</td> </tr> <tr> <td>$0.20 < \varphi \leq 0.30$</td> <td>4</td> </tr> <tr> <td>$0.30 < \varphi \leq 0.50$</td> <td>1</td> </tr> <tr> <td>$0.50 < \varphi$</td> <td>None</td> </tr> </tbody> </table>	Diameter	Acc. Qty	$\varphi \leq 0.20$	Ignore	$0.20 < \varphi \leq 0.30$	4	$0.30 < \varphi \leq 0.50$	1	$0.50 < \varphi$	None
Diameter	Acc. Qty											
$\varphi \leq 0.20$	Ignore											
$0.20 < \varphi \leq 0.30$	4											
$0.30 < \varphi \leq 0.50$	1											
$0.50 < \varphi$	None											
12	Dent on Polarizer (Minor defect)	<table border="1" data-bbox="758 806 1225 1019"> <thead> <tr> <th>Diameter</th> <th>Acc. Qty</th> </tr> </thead> <tbody> <tr> <td>$\varphi \leq 0.20$</td> <td>Ignore</td> </tr> <tr> <td>$0.20 < \varphi \leq 0.30$</td> <td>4</td> </tr> <tr> <td>$0.30 < \varphi \leq 0.50$</td> <td>1</td> </tr> <tr> <td>$0.50 < \varphi$</td> <td>None</td> </tr> </tbody> </table>	Diameter	Acc. Qty	$\varphi \leq 0.20$	Ignore	$0.20 < \varphi \leq 0.30$	4	$0.30 < \varphi \leq 0.50$	1	$0.50 < \varphi$	None
Diameter	Acc. Qty											
$\varphi \leq 0.20$	Ignore											
$0.20 < \varphi \leq 0.30$	4											
$0.30 < \varphi \leq 0.50$	1											
$0.50 < \varphi$	None											
13	Bezel	<p>13.1 No rust, distortion on the Bezel. 13.2 No visible fingerprints, stains or other contamination.</p>										
14	Touch Panel	<p>D: Diameter W: width L: length 14.1 Spot: $D < 0.25$ is acceptable $0.25 \leq D \leq 0.4$ 2dots are acceptable and the distance between defects should more than 10 mm. $D > 0.4$ is unacceptable 14.2 Dent: $D > 0.40$ is unacceptable 14.3 Scratch: $W \leq 0.03, L \leq 10$ is acceptable, $0.03 < W \leq 0.10, L \leq 10$ is acceptable Distance between 2 defects should more than 10 mm. $W > 0.10$ is unacceptable.</p>										
15	PCB	<p>15.1 No distortion or contamination on PCB terminals. 15.2 All components on PCB must same as documented on the BOM/component layout. 15.3 Follow IPC-A-600F.</p>										
16	Soldering	Follow IPC-A-610C standard										
17	Electrical Defect (Major defect)	<p>The below defects must be rejected. 17.1 Missing vertical / horizontal segment, 17.2 Abnormal Display. 17.3 No function or no display.</p>										

		17.4 Current exceeds product specifications. 17.5 LCD viewing angle defect. 17.6 No Backlight. 17.7 Dark Backlight. 17.8 Touch Panel no function.
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Remark: LCD Panel Broken shall be rejected. Defect out of LCD viewing area is acceptable.

10.7. Classification of Defects

- 10.7.1. Visual defects (Except no / wrong label) are treated as minor defect and electrical defect is major.
- 10.7.2. Two minor defects are equal to one major in lot sampling inspection.

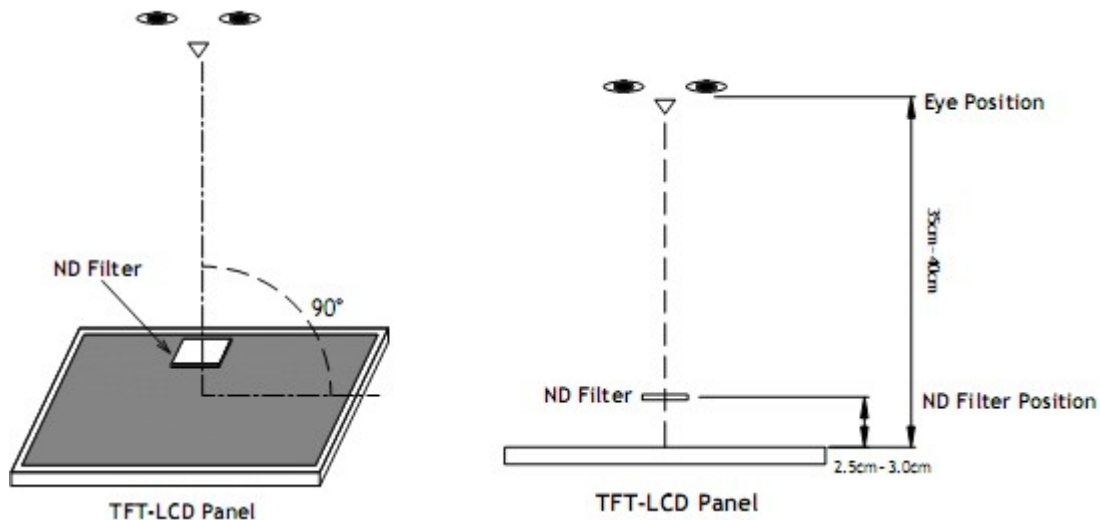
10.8. Identification/marketing criteria

Any unit with illegible / wrong /double or no marking/ label shall be rejected.

10.9. Packaging

- 10.9.1. There should be no damage of the outside carton box, each packaging box should have one identical label.
- 10.9.2. Modules inside package box should have compliant mark.
- 10.9.3. All direct package materials shall offer ESD protection

Note1: Bright dot is defined as the defective area of the dot is larger than 50% of one sub-pixel area.



Bright dot: The bright dot size defect at black display pattern. It can be recognized by 2% transparency of filter when the distance between eyes and panel is 350mm±50mm.

Dark dot: Cyan, Magenta or Yellow dot size defect at white display pattern. It can be recognized by 5% transparency of filter when the distance between eyes and panel is 350mm±50mm.

Note2: Mura on display which appears darker / brighter against background brightness on parts of display area.

11. Reliability Specification

No	Item	Condition	Quantity	Criteria
1	High Temperature Operating	+70°C, 96Hrs	2	GB/T2423.2-2008
2	Low Temperature Operating	-20°C, 96Hrs	2	GB/T2423.1-2008
3	High Humidity	+50°C, 90%RH, 96Hrs	2	GB/T2423.3-2006
4	High Temperature Storage	+80°C, 96Hrs	2	GB/T2423.2-2008
5	Low Temperature Storage	-30°C, 96Hrs	2	GB/T2423.1-2008
6	Thermal Cycling Test	-20°C, 60min~+70°C, 60min, 20 cycles.	2	GB/T2423.22-2012
7	Packing Vibration	Frequency range:10Hz~50Hz Acceleration of gravity:5G X, Y, Z 30 min for each direction.	2	GB/T5170.14-2009
8	Electrical Static Discharge	Air: $\pm 8\text{kV } 150\text{pF}/330\ \Omega$ 5 times Contact: $\pm 4\text{kV } 150\text{pF}/330\ \Omega$ 5 times	2	GB/T17626.2-2006
9	Drop Test (Packaged)	Height: 80 cm,1 corner, 3 edges, 6 surfaces.	2	GB/T2423.8-1995

Note1. No deflection cosmetic and operational function allowable.

Note2. Total current Consumption should be below double of initial value.

12. Precautions and Warranty

12.1.Safety

- 12.1.1. The liquid crystal in the LCD is poisonous. Do not put it in your mouth. If the liquid crystal touches your skin or clothes, wash it off immediately using soap and water.
- 12.1.2. Since the liquid crystal cells are made of glass, do not apply strong impact on them. Handle with care.

12.2.Handling

- 12.2.1. Reverse and use within ratings in order to keep performance and prevent damage.
- 12.2.2. Do not wipe the polarizer with dry cloth, as it might cause scratch. If the surface of the LCD needs to be cleaned, wipe it swiftly with cotton or other soft cloth soaked with petroleum IPA, do not use other chemicals.

12.3.Storage

- 12.3.1. Do not store the LCD module beyond the specified temperature ranges.
- 12.3.2. Strong light exposure causes degradation of polarizer and color filter.

12.4.Metal Pin (Apply to Products with Metal Pins)

- 12.4.1. Pins of LCD and Backlight
 - 12.4.1.1. Solder tip can touch and press on the tip of Pin LEAD during the soldering

12.4.1.2. Recommended Soldering Conditions

Solder Type: Sn96.3~94-Ag3.3~4.3-Cu0.4~1.1

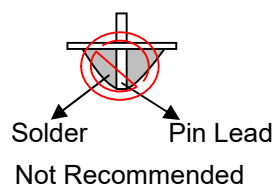
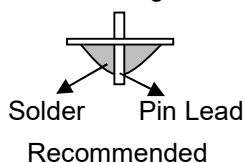
Maximum Solder Temperature: 370°C

Maximum Solder Time: 3s at the maximum temperature

Recommended Soldering Temp: 350±20°C

Typical Soldering Time: ≤3s

12.4.1.3. Solder Wetting



12.4.2. Pins of EL

- 12.4.2.1. Solder tip can touch and press on the tip of EL leads during soldering.
- 12.4.2.2. No Solder Paste on the soldering pad on the motherboard is recommended.

12.4.2.3. Recommended Soldering Conditions

Solder type: Nippon Alimit Leadfree SR-34, size 0.5mm

Recommended Solder Temperature: 270~290°C

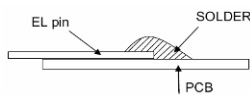
Typical Soldering Time: ≤2s

Minimum solder distance from EL lamp (body):2.0mm

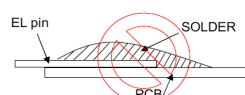
- 12.4.2.4. No horizontal press on the EL leads during soldering.

- 12.4.2.5. 180° bend EL leads three times is not allowed.

12.4.2.6. Solder Wetting

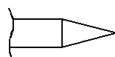


Recommended

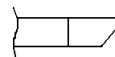


Not Recommended

12.4.2.7. The type of the solder iron:

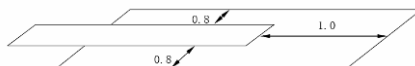


Recommended



Not Recommended

12.4.2.8. Solder Pad



12.5.Operation

- 12.5.1. Do not drive LCD with DC voltage
- 12.5.2. Response time will increase below lower temperature
- 12.5.3. Display may change color with different temperature
- 12.5.4. Mechanical disturbance during operation, such as pressing on the display area, may cause the segments to appear “fractured”.
- 12.5.5. Do not connect or disconnect the LCM to or from the system when power is on.
- 12.5.6. Never use the LCM under abnormal condition of high temperature and high humidity.
- 12.5.7. Module has high frequency circuits. Sufficient suppression to the electromagnetic interface shall be done by system manufacturers. Grounding and shielding methods may be important to minimize the interference.
- 12.5.8. Do not display the fixed pattern for long time (we suggest the time not longer than one hour) because it may develop image sticking due to the TFT structure.

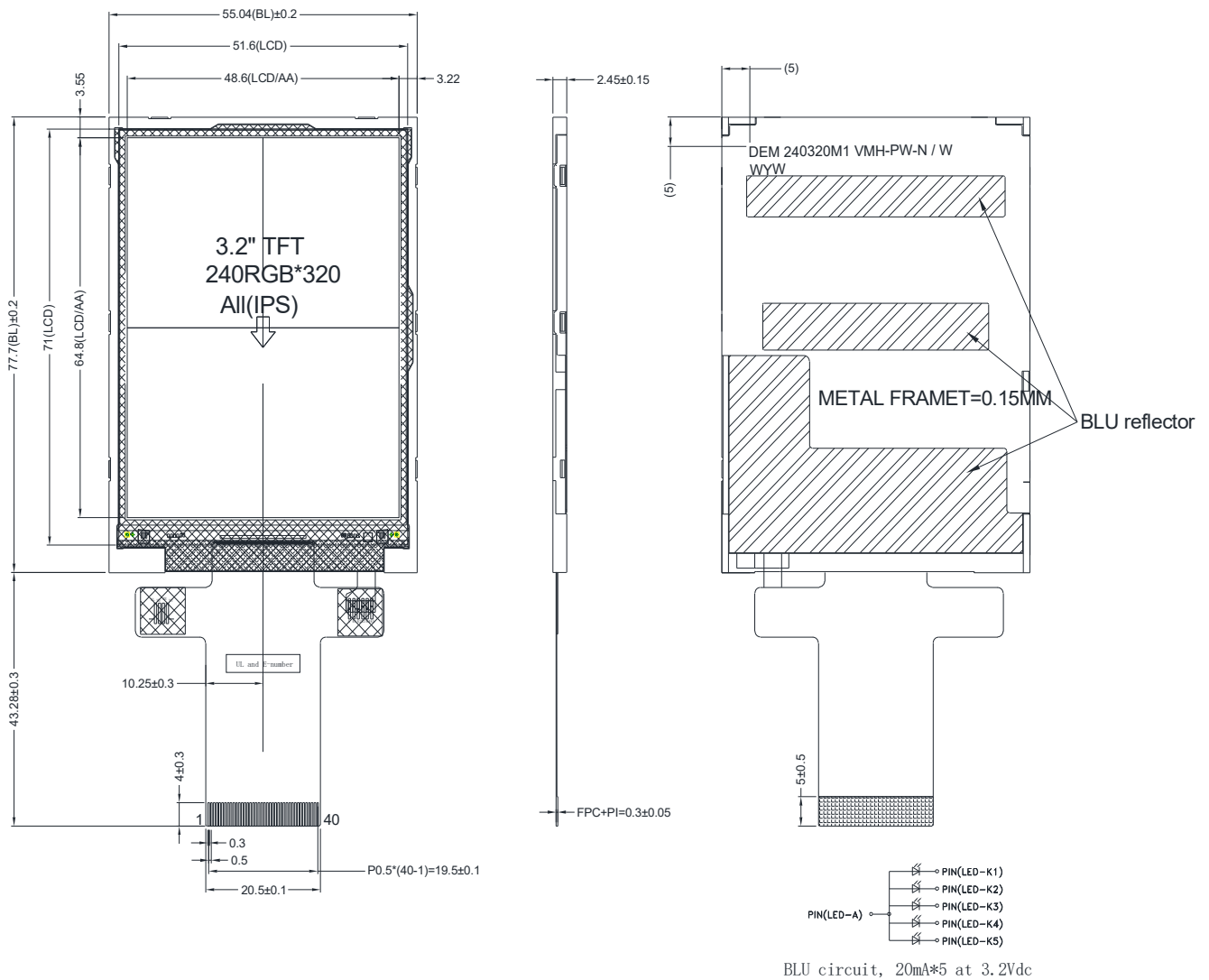
12.6.Static Electricity

- 12.6.1. CMOS LSIs are equipped in this unit, so care must be taken to avoid the electro-static charge, by ground human body, etc.
- 12.6.2. The normal static prevention measures should be observed for work clothes and benches.
- 12.6.3. The module should be kept into anti-static bags or other containers resistant to static for storage.

12.7.Limited Warranty

- 12.7.1. Our warranty liability is limited to repair and/or replacement. We will not be responsible for any consequential loss.
- 12.7.2. If possible, we suggest customer to use up all modules in six months. If the module storage time over twelve months, we suggest that recheck it before the module be used
- 12.7.3. After the product shipped, any product quality issues must be feedback within three months, otherwise, we will not be responsible for the subsequent or consequential events.

13. Outline Drawing



INTERFACE MODE SELECT
RESISTANCE SWITCHING

	IM0	IM1	IM2
GND	R2	R4	R6
IOVCC	R1	R3	R5
PIN	R7-PIN38	R8-39PIN	R9-PIN40